

N&P-Channel V Complementary MOSFET

Description

The HM609K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

N channel

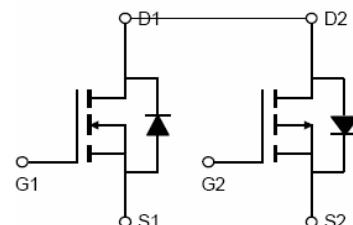
- $V_{DS} = 40V, I_D = 30A$
 $R_{DS(ON)} < 16m\Omega @ V_{GS}=10V$
 $R_{DS(ON)} < 24m\Omega @ V_{GS}=4.5V$

p channel

- $V_{DS} = -40V, I_D = -18A$
 $R_{DS(ON)} < 45m\Omega @ V_{GS}=-10V$
 $R_{DS(ON)} < 65m\Omega @ V_{GS}=-4.5V$
- High density cell design for ultra low $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- H-bridge
- Inverters



Schematic diagram



Marking and pin assignment

100% UIS TESTED!

100% ΔV_{ds} TESTED!

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|--------|----------------|-----------|------------|----------|
| HM609K | HM609K | TO-252-4L | - | - | - |

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

| Parameter | Symbol | N-Channel | P-Channel | Unit |
|--|----------------|------------|-----------|------|
| Drain-Source Voltage | V_{DS} | 40 | -40 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | ± 20 | V |
| Continuous Drain Current $T_c=25^\circ C$ | I_D | 30 | -18 | A |
| $T_c=100^\circ C$ | | 21 | -12.6 | |
| Pulsed Drain Current (Note 1) | I_{DM} | 90 | -54 | A |
| Maximum Power Dissipation | P_D | 21 | | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 175 | | °C |

Thermal Characteristic

| | | | |
|--|-----------------|---|------|
| Thermal Resistance, Junction-to-Case ^(Note 2) | $R_{\theta JC}$ | 7 | °C/W |
|--|-----------------|---|------|

N-Channel Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|----------------------------|--|-----|------|-----------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$ | 40 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$ | - | - | ± 100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$ | 1.2 | 1.5 | 2.2 | V |
| Drain-Source On-State Resistance | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=10\text{V}, I_{\text{D}}=7\text{A}$ | - | 12.9 | 16 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=6\text{A}$ | - | 18.9 | 24 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{DS}}=10\text{V}, I_{\text{D}}=7\text{A}$ | - | 29 | - | S |
| Dynamic Characteristics (Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$ | - | 450 | - | PF |
| Output Capacitance | C_{oss} | | - | 150 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 90 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}}=15\text{V}, R_{\text{L}}=2.5\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=3\Omega$ | - | 5 | - | nS |
| Turn-on Rise Time | t_{r} | | - | 12 | - | nS |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 19 | - | nS |
| Turn-Off Fall Time | t_{f} | | - | 6 | - | nS |
| Total Gate Charge | Q_{g} | $V_{\text{DS}}=15\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=10\text{V}$ | - | 9.5 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 2.0 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 1.9 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V_{SD} | $V_{\text{GS}}=0\text{V}, I_{\text{S}}=30\text{A}$ | - | | 1.2 | V |
| Diode Forward Current (Note 2) | I_{S} | | - | - | 30 | A |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_j=25^\circ\text{C}, V_{\text{DD}}=40\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

N-Channel Typical Electrical and Thermal Characteristics (Curves)

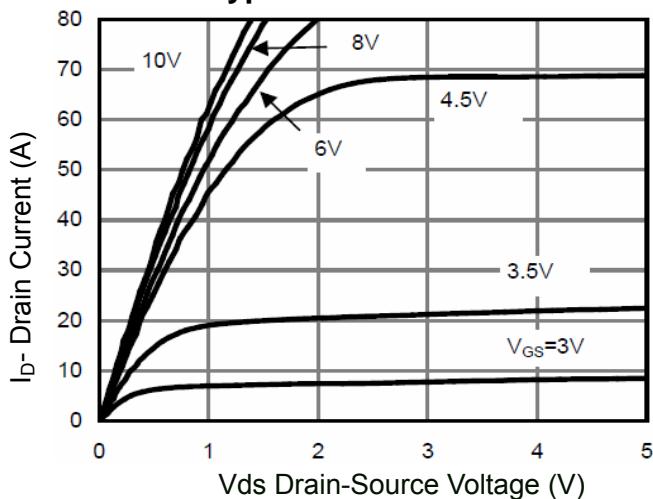


Figure 1 Output Characteristics

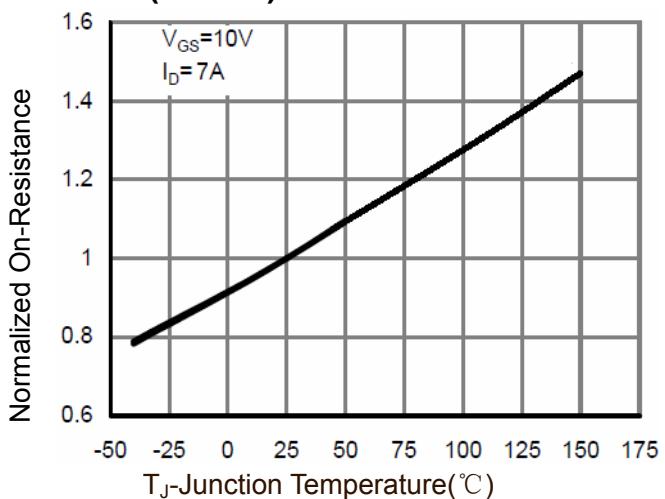


Figure 4 Rdson-Junction Temperature

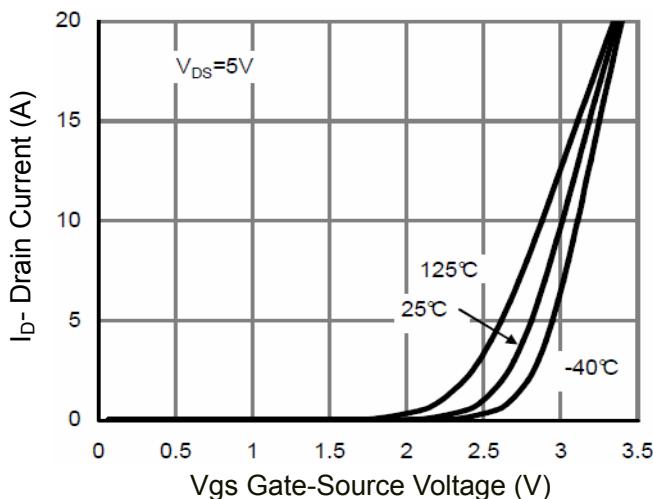


Figure 2 Transfer Characteristics

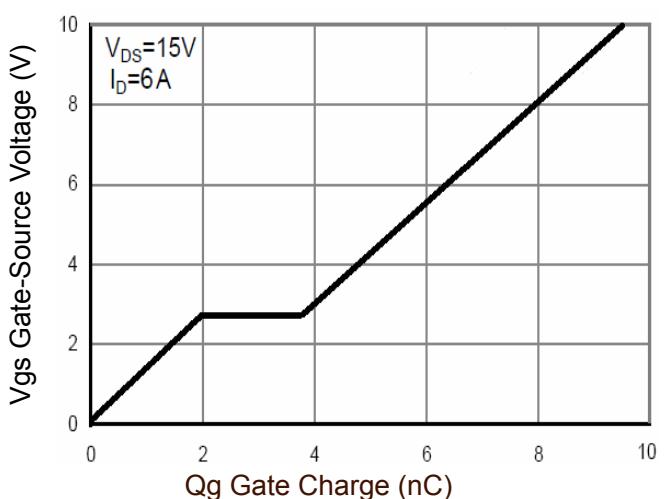


Figure 5 Gate Charge

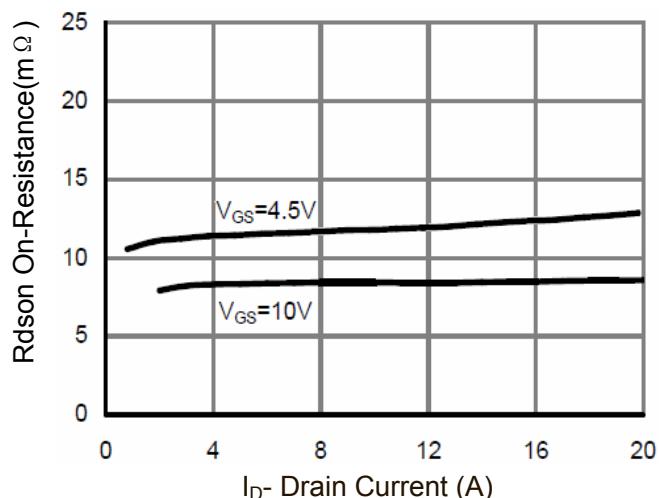


Figure 3 Rdson- Drain Current

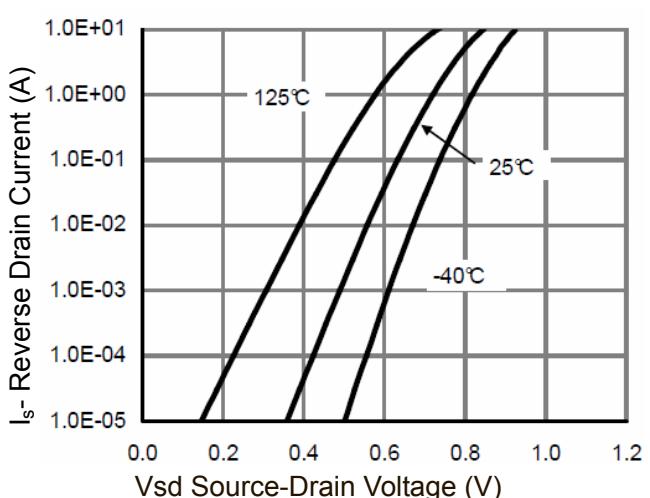


Figure 6 Source- Drain Diode Forward

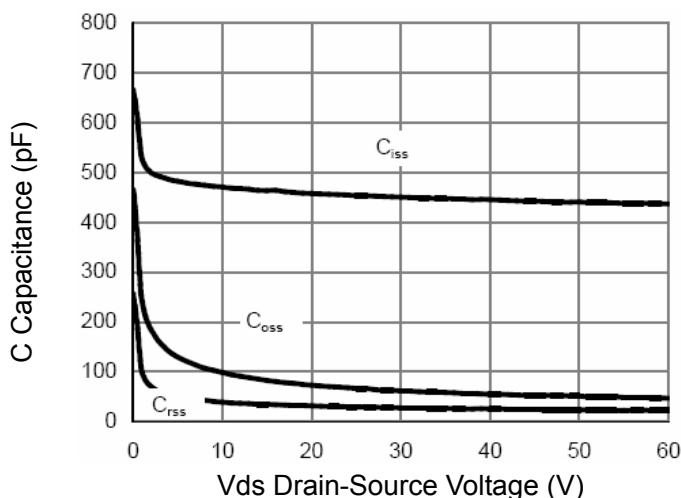


Figure 7 Capacitance vs Vds

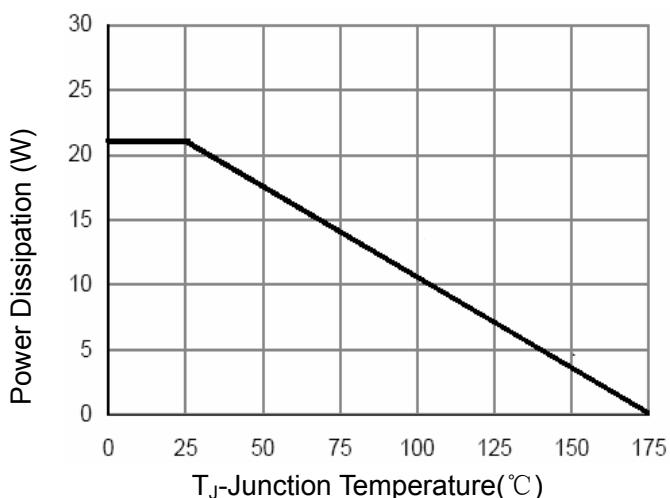


Figure 9 Figure 9 Power De-rating

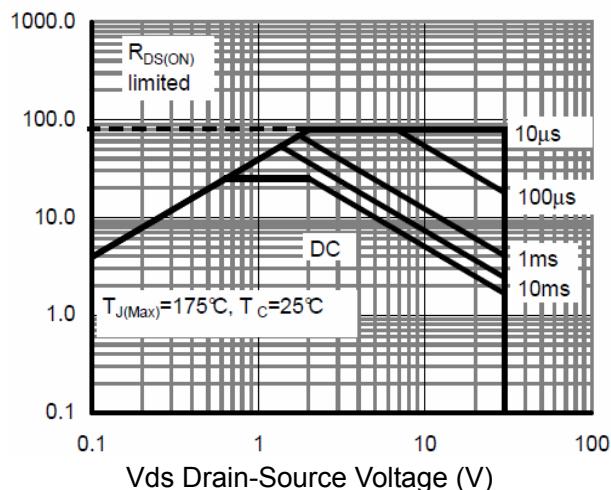


Figure 8 Safe Operation Area

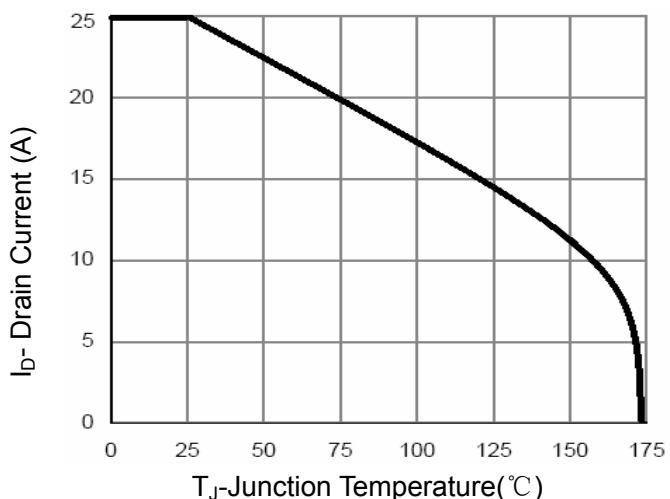
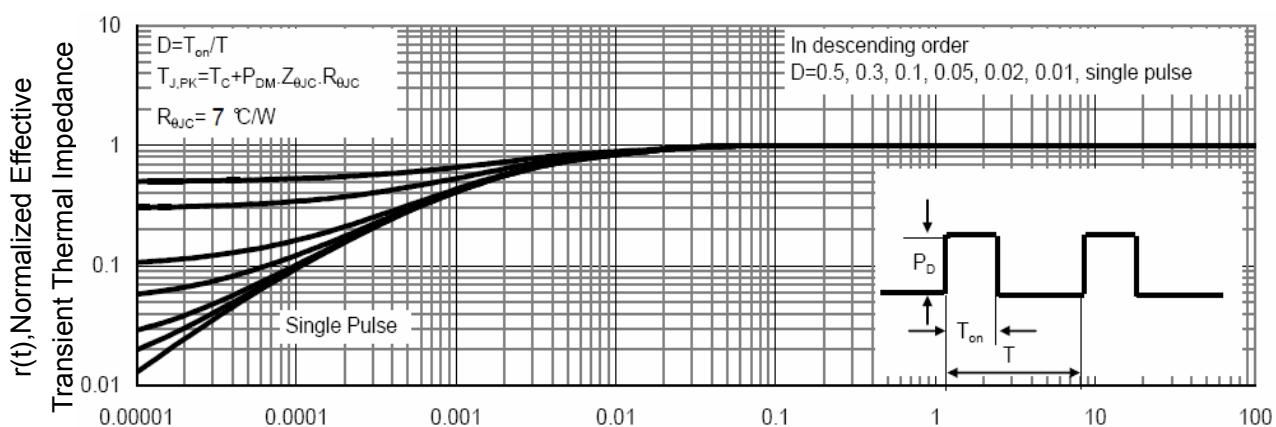


Figure 10 Current De-rating



Square Wave Pulse Duration(sec)
Figure 11 Normalized Maximum Transient Thermal Impedance

P-Channel Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|-----------------------------------|--|------|------|----------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=-250\mu\text{A}$ | -40 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $\text{V}_{\text{DS}}=-40\text{V}, \text{V}_{\text{GS}}=0\text{V}$ | - | - | -1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$ | - | - | ±100 | nA |
| On Characteristics <small>(Note 3)</small> | | | | | | |
| Gate Threshold Voltage | $\text{V}_{\text{GS}(\text{th})}$ | $\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=-250\mu\text{A}$ | -1.3 | - | -2.5 | V |
| Drain-Source On-State Resistance | $\text{R}_{\text{DS}(\text{ON})}$ | $\text{V}_{\text{GS}}=-10\text{V}, \text{I}_D=-6\text{A}$ | - | - | 45 | $\text{m}\Omega$ |
| | | $\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-5\text{A}$ | | - | 65 | |
| Forward Transconductance | g_{FS} | $\text{V}_{\text{DS}}=-5\text{V}, \text{I}_D=-6\text{A}$ | - | 15 | - | S |
| Dynamic Characteristics <small>(Note 4)</small> | | | | | | |
| Input Capacitance | C_{iss} | $\text{V}_{\text{DS}}=-40\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $F=1.0\text{MHz}$ | - | 920 | - | PF |
| Output Capacitance | C_{oss} | | - | 140 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 90 | - | PF |
| Switching Characteristics <small>(Note 4)</small> | | | | | | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $\text{V}_{\text{DD}}=-15\text{V}, \text{R}_L=2.5\Omega$ $\text{V}_{\text{GS}}=-10\text{V}, \text{R}_G=3\Omega$ | - | 8 | - | nS |
| Turn-on Rise Time | t_r | | - | 30 | - | nS |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 22 | - | nS |
| Turn-Off Fall Time | t_f | | - | 26 | - | nS |
| Total Gate Charge | Q_g | $\text{V}_{\text{DS}}=-15\text{V}, \text{I}_D=-6\text{A},$ $\text{V}_{\text{GS}}=-10\text{V}$ | - | 16.2 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 2.9 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 3.6 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage <small>(Note 3)</small> | V_{SD} | $\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=-6\text{A}$ | - | | -1.2 | V |
| Diode Forward Current <small>(Note 2)</small> | I_s | | - | - | -18 | A |
| Reverse Recovery Time | t_{rr} | $\text{TJ} = 25^\circ\text{C}, \text{IF} = -6\text{A}$ $d\text{i}/dt = 100\text{A}/\mu\text{s}$ <small>(Note 3)</small> | - | 23 | - | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 14 | - | nC |

P-Channel Typical Electrical and Thermal Characteristics (Curves)

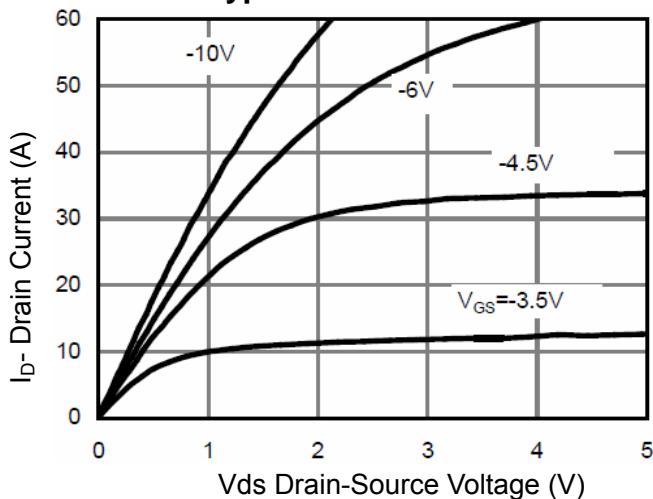


Figure 1 Output Characteristics

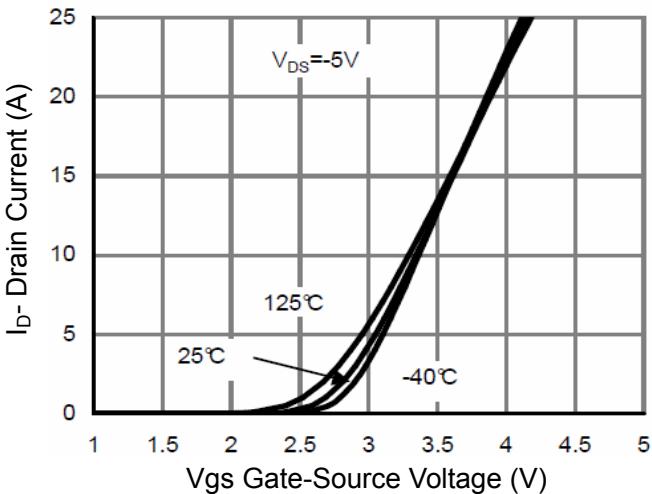


Figure 2 Transfer Characteristics

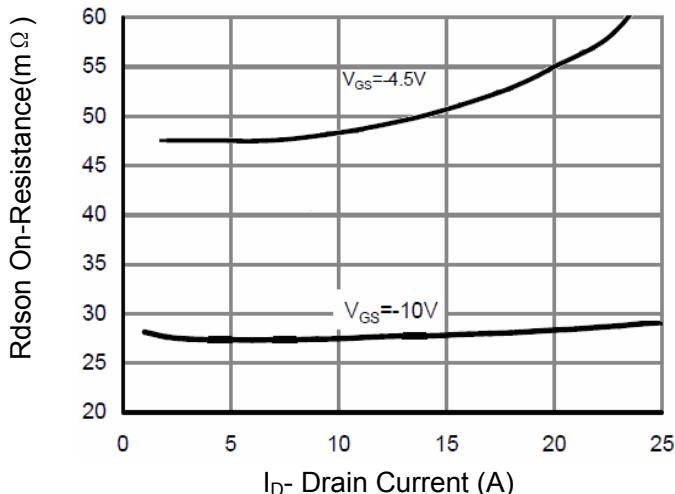


Figure 3 Rdson- Drain Current

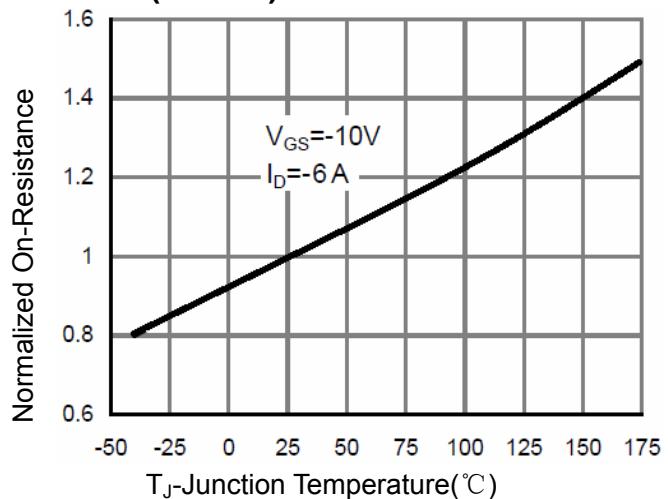


Figure 4 Rdson-Junction Temperature

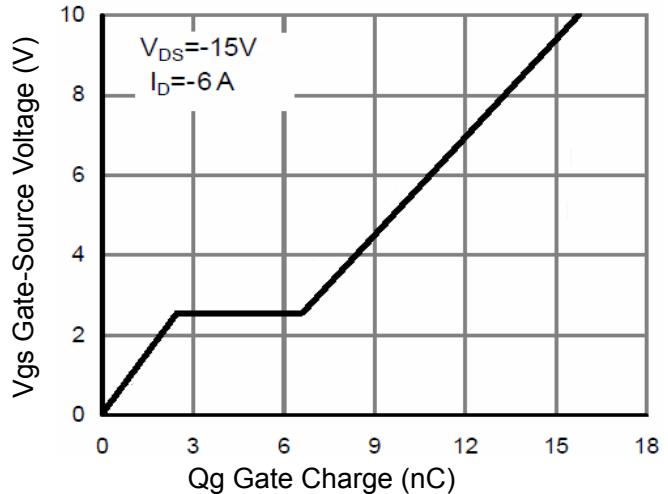


Figure 5 Gate Charge

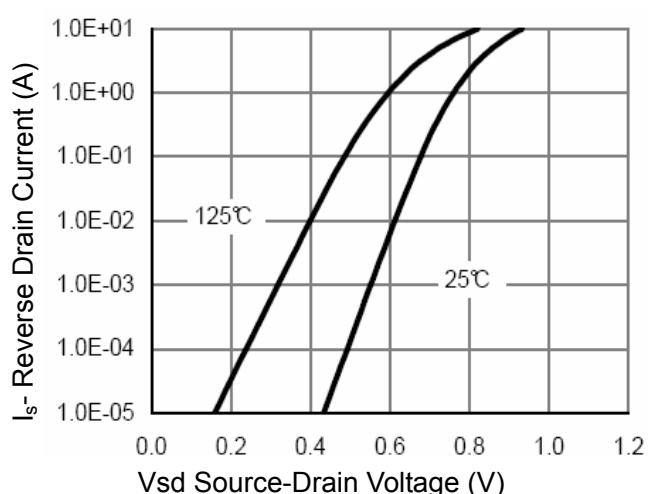


Figure 6 Source- Drain Diode Forward

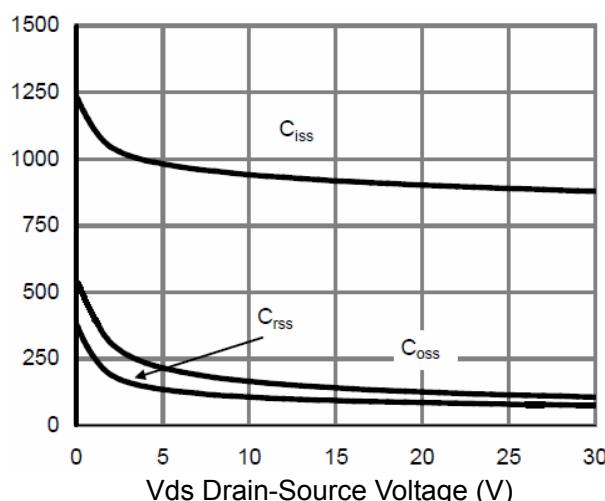


Figure 7 Capacitance vs Vds

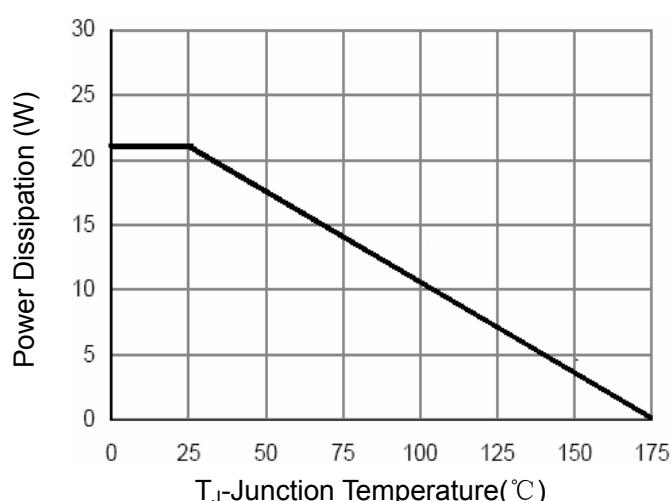


Figure 9 Power De-rating

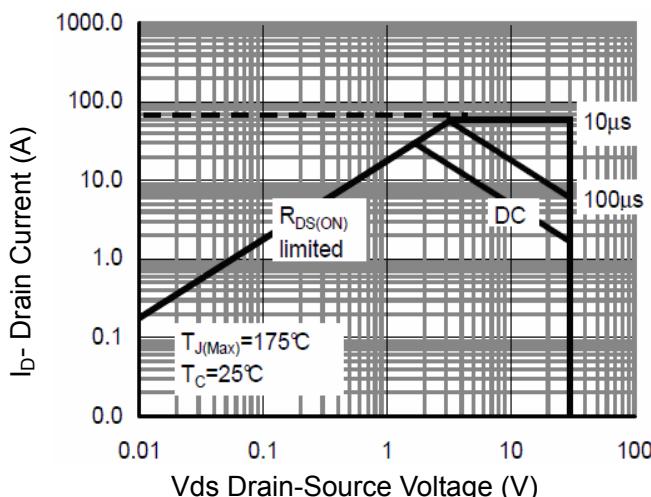


Figure 8 Safe Operation Area

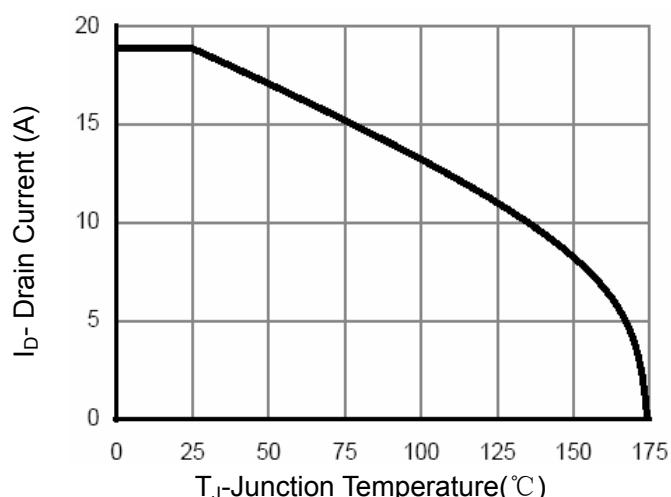


Figure 10 Current De-rating

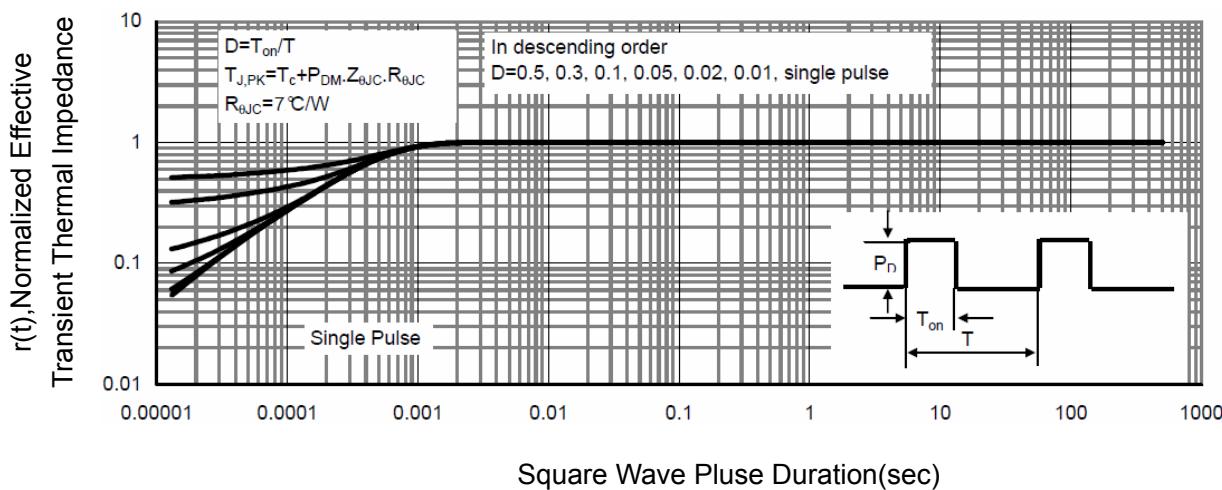
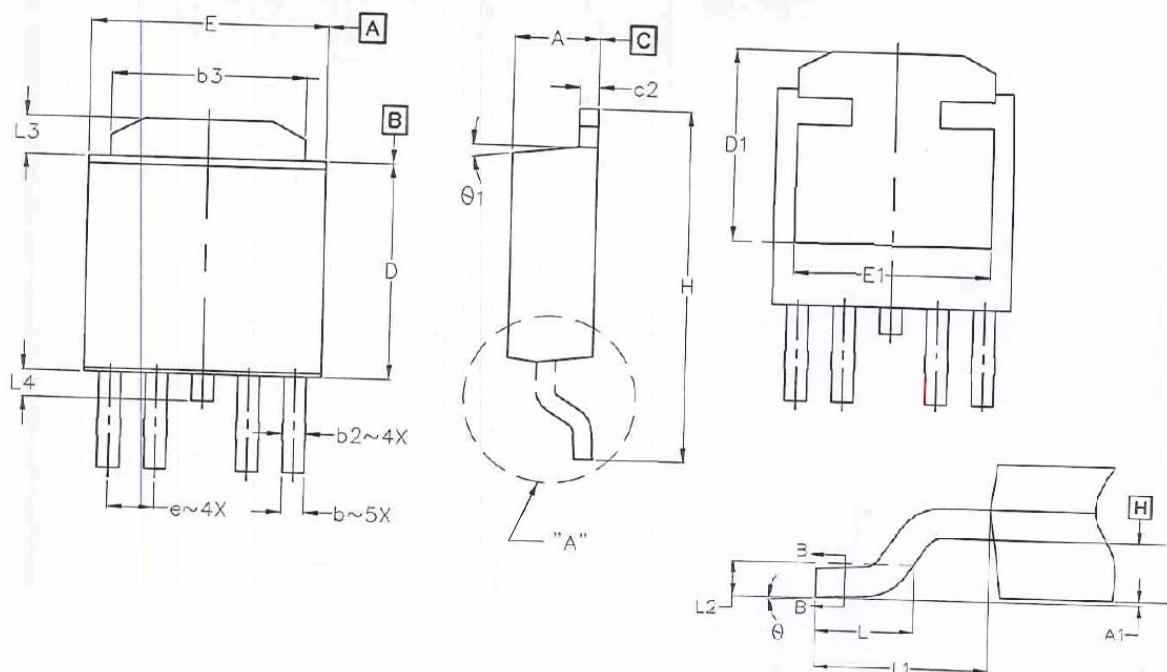


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252-4L Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.184 | 2.387 | 0.086 | 0.094 |
| A1 | - | 0.127 | - | 0.094 |
| b | 0.508 | 0.711 | 0.020 | 0.028 |
| b1 | 0.508 | 0.660 | 0.020 | 0.026 |
| b2 | 0.610 | 0.787 | 0.024 | 0.031 |
| b3 | 4.953 | 5.461 | 0.195 | 0.215 |
| c | 0.460 | 0.610 | 0.018 | 0.024 |
| c1 | 0.410 | 0.559 | 0.016 | 0.022 |
| C2 | 0.460 | 12.950 | 0.498 | 0.510 |
| D | 4.980 | 5.180 | 0.196 | 0.204 |
| D1 | 2.650 | 2.950 | 0.104 | 0.116 |
| E | 7.900 | 8.100 | 0.311 | 0.319 |
| E1 | 0.000 | 0.300 | 0.000 | 0.012 |
| e | 12.900 | 13.400 | 0.508 | 0.528 |
| H | 2.850 | 3.250 | 0.112 | 0.128 |
| L | 1.397 | 1.778 | 0.055 | 0.070 |
| L1 | 2.743 | BSC | 0.108 | BSC |
| L2 | 0.508 | BSC | 0.020 | BSC |
| L3 | 0.889 | 1.270 | 0.035 | 0.050 |
| L4 | - | 1.015 | - | 0.040 |
| θ | 0° | 10° | 0° | 10° |
| θ1 | 0° | 15° | 0° | 15° |